

SMIC High Quality Flow Soldering System

New Stable Pressure Flow Soldering machine ECOPASCAL SPF-300

[PAT.P]

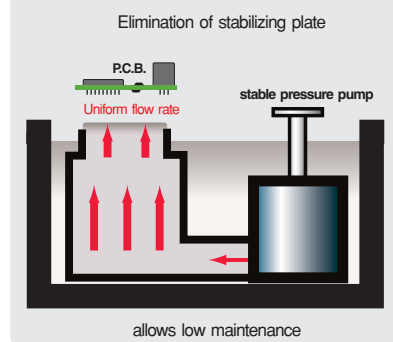
The latest stable pressure flow soldering machine is most suitable for high quality lead-free soldering



Features

- Eliminating a use of stabilizing plate enables smooth and stable wave for best soldering process with easy maintenance.
- High flow pressure provides sufficient solder in through-holes of multilayer boards and significantly reduces missing solders and bridges.
- Suitable for high thermal capacity devices allowing sufficient heat supply for soldering.
- Flow height can be easily set and maintained at 15mm or above.
- Vertical adjustment of the conveyer rail provides flexibility and allows easy cleaning of the top without removal.
- Soldering process is visible through glass hood for better monitoring purpose.
- Standard touch panel operation allows changing among Japanese, English, or Chinese.
- New lineup of 4 models for 300^m/m, 350^m/m, 400^m/m, and 24 inches PCB widths.

Stable pressure flow (SPF)



SPF-300 Standard Specification

● Dimensions	3,650mm (L) × 1,330mm (W) × 1,460mm (H)	● Board dimensions	50 (W) × 100 (L) mm to 300 (W) × 350 (L) mm
● Conveyer	Angle setting : 5° Variable conveyer width by manual operation	● Controller	PLC + PC controlled touch panel
● Pass line	780mm	● Weight	1,700 kg (approx.) solder included
● Preheater	Far infrared rays panel heaters (2.4kW×3)	● Power supply	3 phase 200V 19.8kw
● Solder bath	Heaters : 0.95kW×12, Anti-splash heater (0.4kW) Solder (M705E, 390Kg)	● Options	Local N ₂ unit, Foam fluxer unit, Chiller unit, High wave nozzle, Available 350mm, 400mm, and 24 inches PCB width

★ Design and specification are subject to change without notice for improvements of system performance. © 2006 SMIC